

Application Engineer (Based in Hicom-Glenmarie)

## **QAM (ASIA-PACIFIC) SDN BHD**

**Sales & Marketing Department**

### **Responsibilities:-**

- Handle FOL wire bonders for semiconductor.
- Fine tune parameters to set optimal condition for capillary.
- Perform capillary qualification.

### **Requirements:-**

- Possess a Diploma or Degree in Electrical & Electronic Engineering or Science related studies.
- 2 - 3 years good copper wire bonding hands on experience.
- Good hands on experience with ASM and/or KnS wire bonders.
- An independent person who can carry out daily duties with minimum supervision.
- A good team player with strong communication and interpersonal skills.
- Possess own transport and willing to travel local and overseas.